Amendments to the Claims

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claims 1-13 (cancelled).

Claim 14 (new). A method of producing a model or tool comprising:

(a) building an assembly of substrates by assembling and adhering at least one substrate to another substrate with a layer of adhesive paste;

(b) optionally machining the assembly of substrates;

(c) covering the outer surface of the assembly of substrates with a continuous layer of curable paste;

(d) curing the layer of curable paste to produce the model or tool

wherein the composition of the curable paste of step (c) is the same as the composition of at least one of the layers of adhesive paste of step (a).

Claim 15 (new). The method of Claim 14, wherein the curable paste is machine dispensed.

Claim 16 (new). The method of Claim 14, wherein the assembly of substrates is a stack assembly of substrates adhered with several intermediate layers of adhesive paste.

Claim 17 (new). The method of Claim 14 wherein the adhesive paste and curable paste are formed by machine mixing at least two separate components.

Claim 18 (new). The method of Claim 14, wherein the adhesive paste and curable paste are thixotropic and have non-slump properties.

Claim 19 (new). The method of Claim 14, wherein the adhesive paste and curable paste have a dynamic viscosity equal to or less than 10,000 mPa s measured at 25°C.

Claim 20 (new). The method of Claim 14, wherein the curable paste is an epoxy paste obtained by mixing an epoxy component and a hardener component.

Claim 21 (new). The method of Claim 14, wherein the curable paste comprises an epoxy component containing a curable epoxy resin and a hardener component containing a latent or semi-latent hardener.

Claim 22 (new). A method of producing a model or tool comprising the sequential steps of:

(a) mixing a first component containing a curable epoxy resin with a second component containing a hardener system to form a curable paste;

(b) applying the curable paste on an outer surface of a substructure in the form of a continuous layer;

(c) curing the continuous layer of curable paste; and

(d) machining the cured continuous layer to produce the model or tool.

Claim 23 (new). The method of Claim 22, wherein the first component further contains a thixotropic agent and wherein the hardener system contains at least one polyethyleneimine, at least one other amine having at least two amino hydrogen groups and at least one other epoxy curative having latent reactivity.

Claim 24 (new). The method of Claim 23, wherein the epoxy curative contains diethyl toluene diamine, dicyandiamide, diphenyl diamino sulphone, boron complexes and/or imidazoles.

Claim 25 (new). The method of Claim 22, wherein the curable paste after curing has a heat deflection temperature above 100°C.

Claim 26 (new). The method of Claim 22, wherein the final cured model or tool is machined to form a model or tool for producing laminated composites.

Claim 27 (new). A method of producing a model or tool comprising:

(a) building an assembly of substrates by assembling and adhering at least one substrate to another substrate with a layer of adhesive paste;

(b) covering the outer surface of the assembly of substrates with a continuous layer of machine dispensed curable paste comprising an epoxy resin, amine hardener and a polyethyleneimine compound;

wherein the composition of the curable paste of step (b) is the same as the composition of at least one of the layers of the adhesive paste of step (a).

Claim 28 (new). A curable composition comprising:

(a) an epoxy resin;

(b) a thixotropic agent; and

(c) a hardener system containing at least one polyethyleneimine compound, at least one other amine having at least two amino hydrogen groups, and at least one other epoxy curative having latent reactivity.